

JAN 10 2001

Attorney's Docket No.: 100-1200-0004-01
1465-77

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hisashi Ohtani Art Unit : 1765
Serial No.: 09/596,755 Examiner : Robert Kunemund
Filed : June 15, 2000
Title : MANUFACTURING METHOD OF SEMICONDUCTOR AND
MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE

Commissioner for Patents
Washington, D.C. 20231

TRANSMITTAL LETTER AND PETITION FOR AUTOMATIC EXTENSION

Correspondence relating to this application is enclosed.
The required fees are computed below. Please apply any charges
not covered, or any credits, to Deposit Account No. 06-1050.

| | | | | | | |
|---------------|----|---|----|---|----|--------------|
| Total Claims | 44 | - | 20 | = | 24 | \$432 |
| Independent | 7 | - | 3 | = | 4 | <u>\$320</u> |
| TOTAL FEE DUE | | | | | | \$752 |

A check for \$752 is attached.

Respectfully submitted,

Date: 1/24/01

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CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner of Patents, Washington, D.C. 20231.

Sincerely,

Susan Regan

Susan Regan
Long Beach Office, US Patent & Trademark Office
Certified 1/24/01

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AMENDMENT

Sir:

In response to the Official Action dated October 24, 2000, Paper No. 2, in the above-referenced application, please amend the above-identified application as follows.

In the Claims:

Please cancel claim 1 without prejudice.

Please add the following new claims.

2. (New) A method for manufacturing a semiconductor device comprising steps of:

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Susan Regan

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